

# PBSS304PZ

60 V, 4.5 A PNP low  $V_{CEsat}$  (BISS) transistor

Rev. 02 — 8 December 2009

Product data sheet

## 1. Product profile

### 1.1 General description

PNP low  $V_{CEsat}$  Breakthrough In Small Signal (BISS) transistor in a SOT223 (SC-73) small Surface-Mounted Device (SMD) plastic package.

NPN complement: PBSS304NZ.

### 1.2 Features

- Low collector-emitter saturation voltage  $V_{CEsat}$
- High collector current capability  $I_C$  and  $I_{CM}$
- High collector current gain ( $h_{FE}$ ) at high  $I_C$
- High efficiency due to less heat generation
- Smaller required Printed-Circuit Board (PCB) area than for conventional transistors

### 1.3 Applications

- High-voltage DC-to-DC conversion
- High-voltage MOSFET gate driving
- High-voltage motor control
- High-voltage power switches (e.g. motors, fans)
- Automotive applications

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### 1.4 Quick reference data

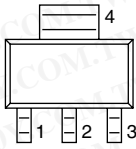
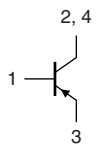
Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CEO}$	collector-emitter voltage	open base	-	-	-60	V
$I_C$	collector current		-	-	-4.5	A
$I_{CM}$	peak collector current	single pulse; $t_p \leq 1$ ms	-	-	-9	A
$R_{CEsat}$	collector-emitter saturation resistance	$I_C = -4$ A; $I_B = -200$ mA	[1] -	53	75	m $\Omega$

[1] Pulse test:  $t_p \leq 300$   $\mu$ s;  $\delta \leq 0.02$ .

## 2. Pinning information

**Table 2. Pinning**

Pin	Description	Simplified outline	Symbol
1	base		
2	collector		
3	emitter		
4	collector		

*sym028*

## 3. Ordering information

**Table 3. Ordering information**

Type number	Package		Version
	Name	Description	
PBSS304PZ	SC-73	plastic surface-mounted package with increased heatsink; 4 leads	SOT223

## 4. Marking

**Table 4. Marking codes**

Type number	Marking code
PBSS304PZ	S304PZ

## 5. Limiting values

**Table 5. Limiting values**

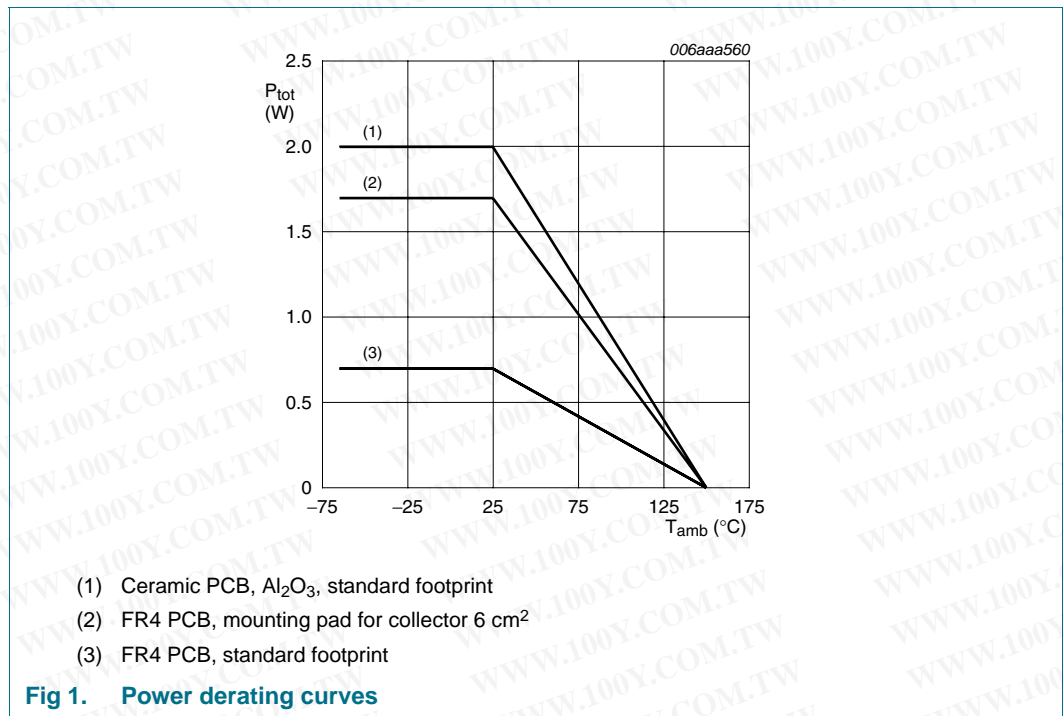
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CBO}$	collector-base voltage	open emitter	-	-60	V
$V_{CEO}$	collector-emitter voltage	open base	-	-60	V
$V_{EBO}$	emitter-base voltage	open collector	-	-5	V
$I_C$	collector current		-	-4.5	A
$I_{CM}$	peak collector current	single pulse; $t_p \leq 1$ ms	-	-9	A
$P_{tot}$	total power dissipation	$T_{amb} \leq 25$ °C	[1]	0.7	W
			[2]	1.7	W
			[3]	2.0	W
$T_j$	junction temperature		-	150	°C
$T_{amb}$	ambient temperature		-65	+150	°C
$T_{stg}$	storage temperature		-65	+150	°C

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 6 cm<sup>2</sup>.

[3] Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint.

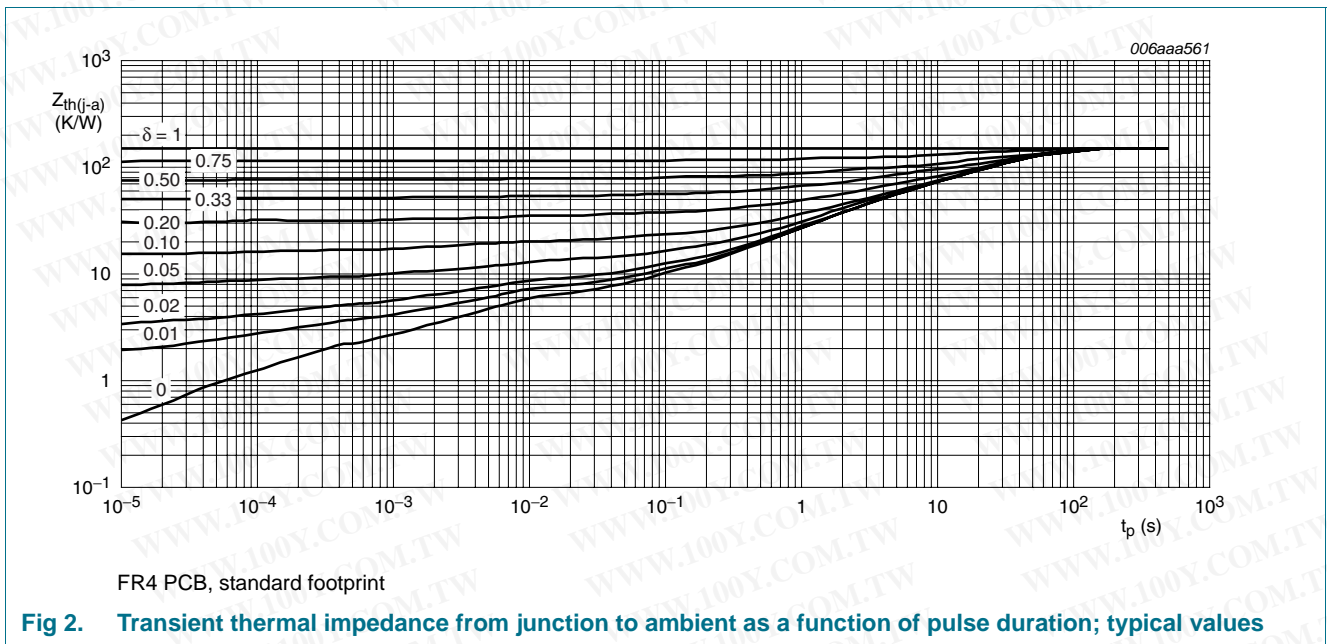


## 6. Thermal characteristics

**Table 6. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	-	179	K/W
			[2]	-	-	74	K/W
			[3]	-	-	63	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		-	-	15	K/W	

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 6 cm<sup>2</sup>.
- [3] Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint.



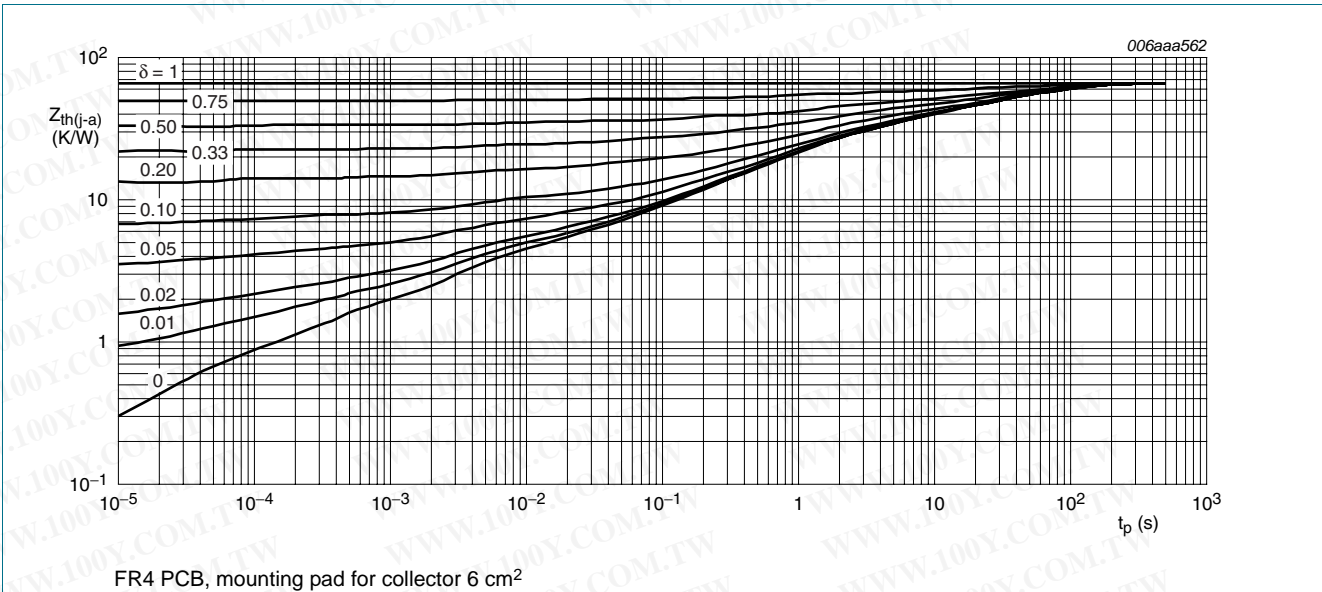


Fig 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

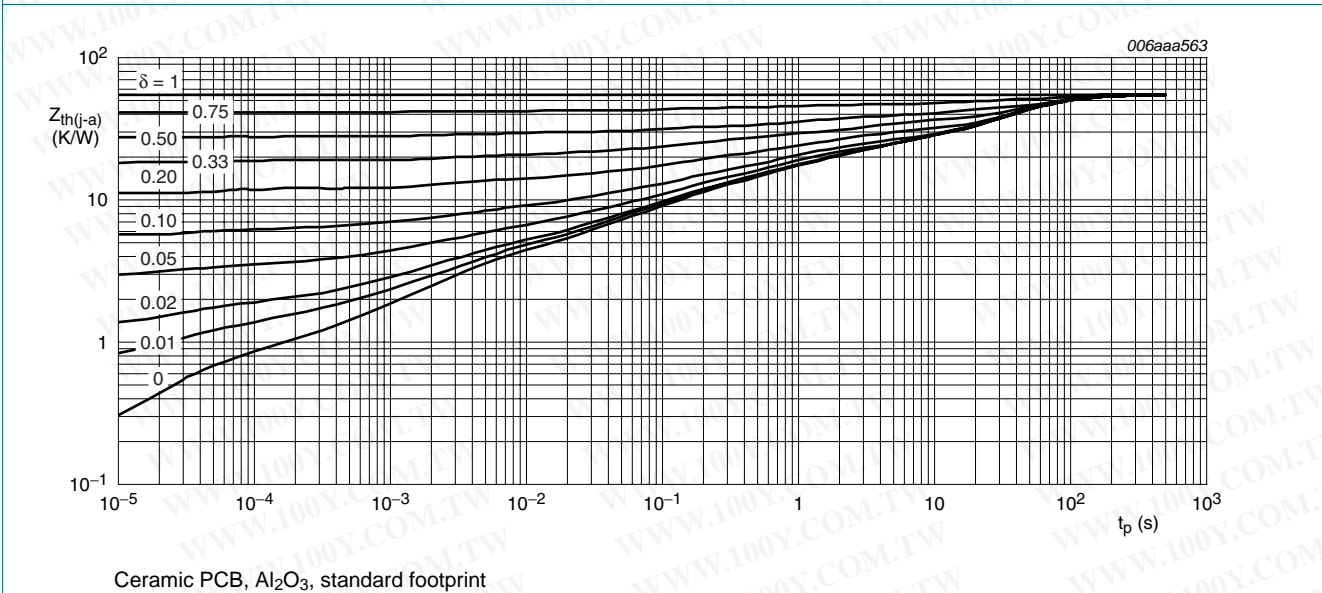


Fig 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

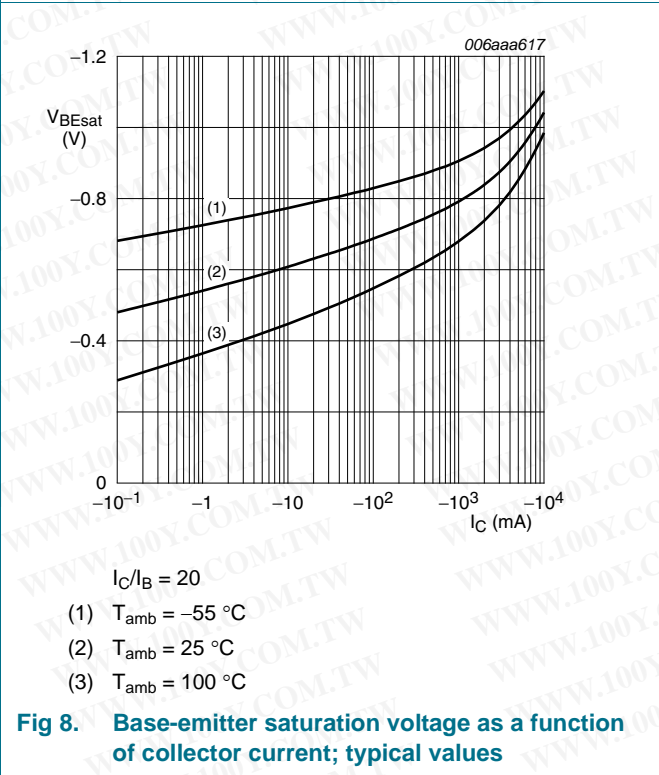
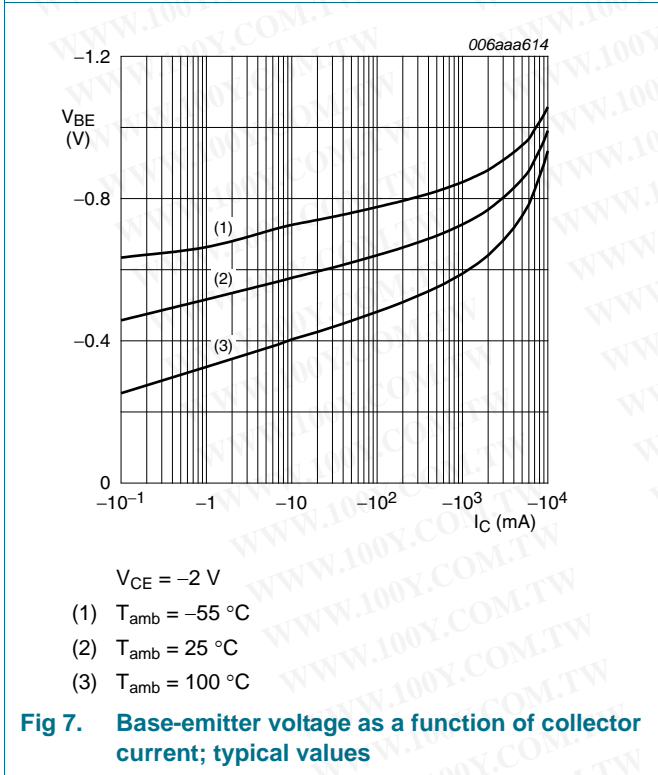
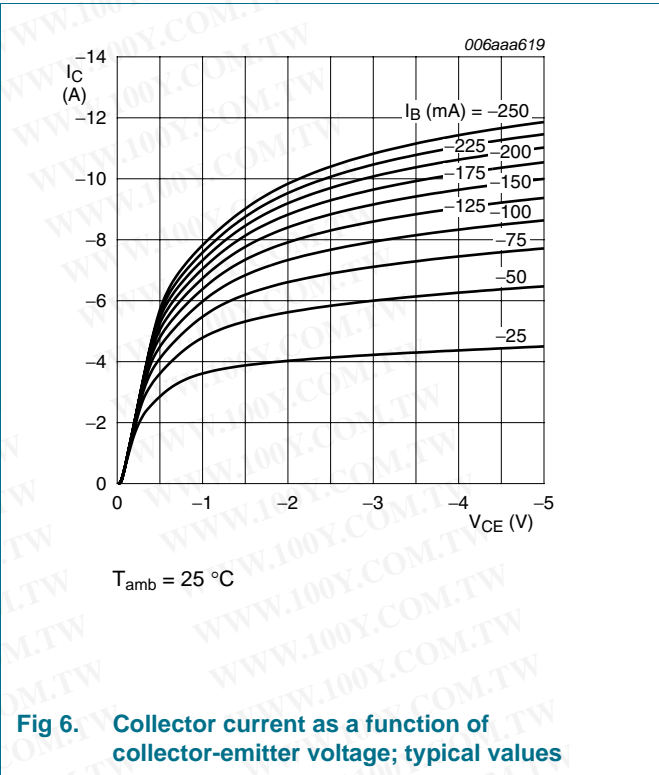
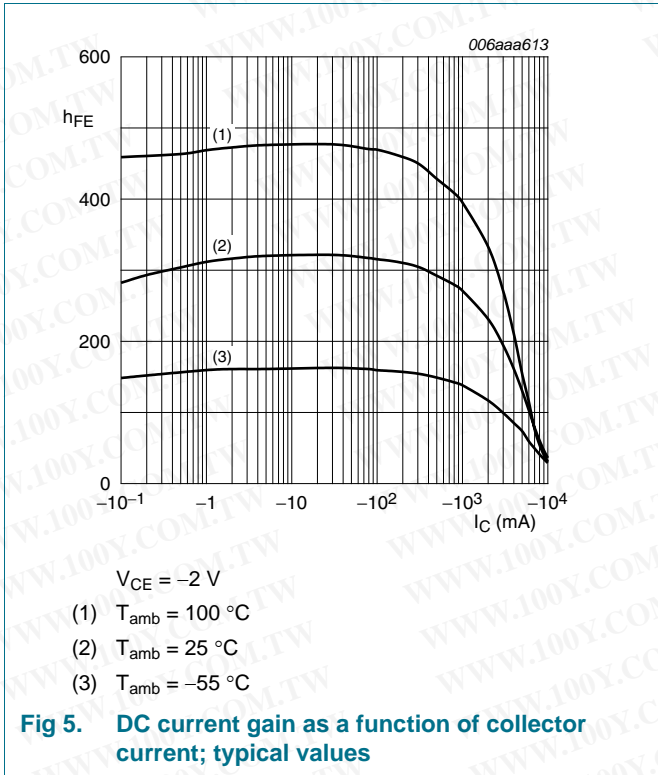


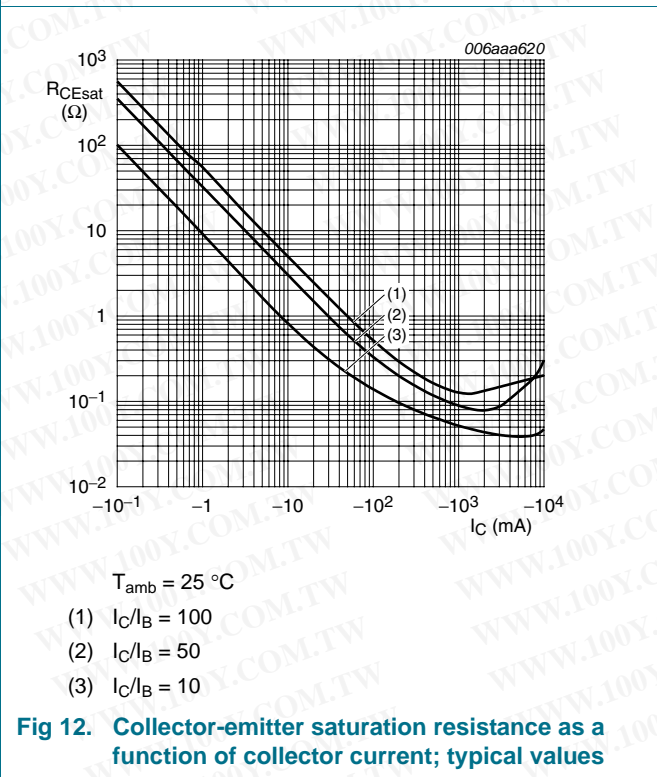
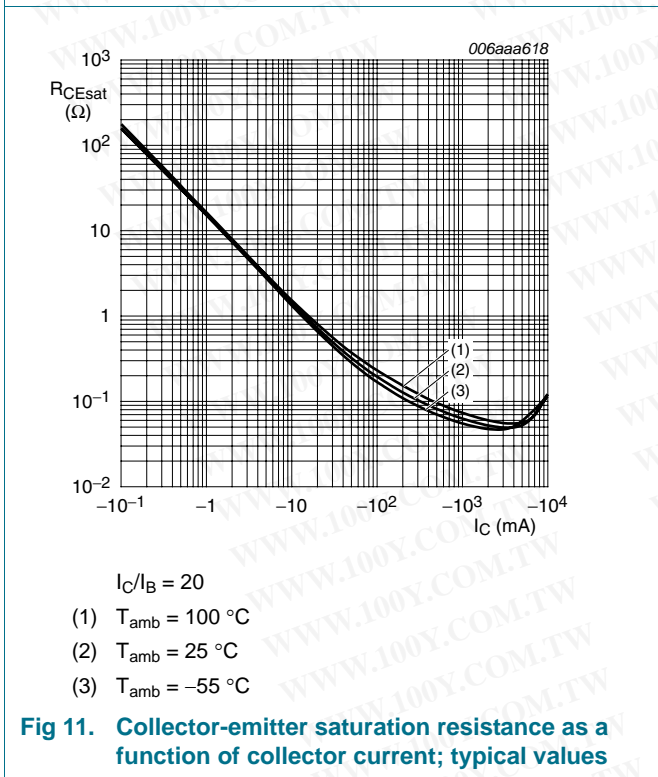
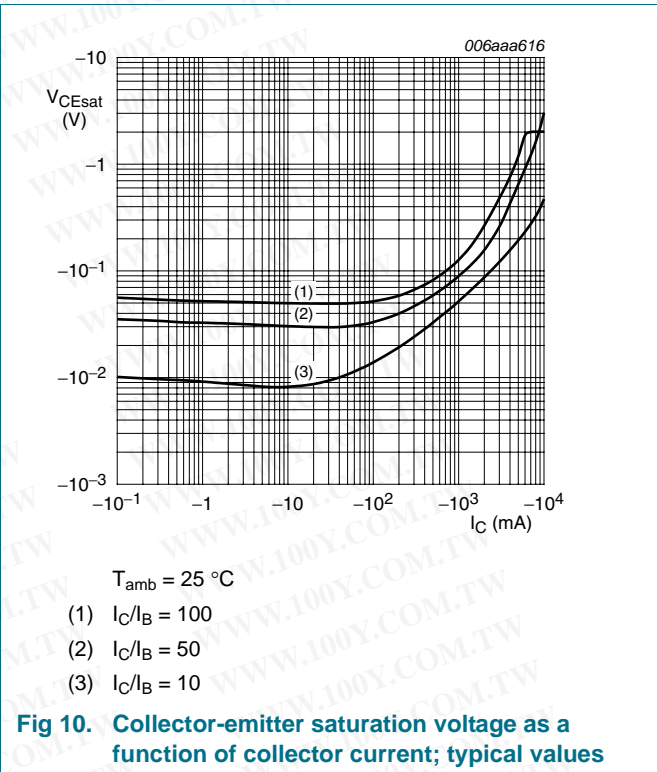
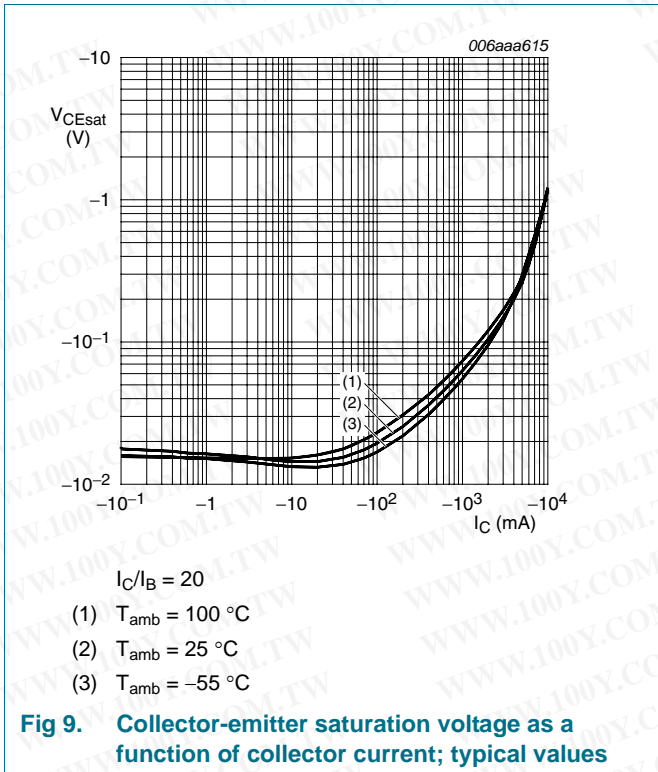
## 7. Characteristics

**Table 7. Characteristics**
 $T_{amb} = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
$I_{CBO}$	collector-base cut-off current	$V_{CB} = -60\text{ V}; I_E = 0\text{ A}$	-	-	-100	nA	
		$V_{CB} = -60\text{ V}; I_E = 0\text{ A}; T_J = 150\text{ }^{\circ}\text{C}$	-	-	-50	$\mu\text{A}$	
$I_{EBO}$	emitter-base cut-off current	$V_{EB} = -5\text{ V}; I_C = 0\text{ A}$	-	-	-100	nA	
$h_{FE}$	DC current gain	$V_{CE} = -2\text{ V}; I_C = -0.5\text{ A}$	[1]	200	295	-	
		$V_{CE} = -2\text{ V}; I_C = -1\text{ A}$	[1]	200	270	-	
		$V_{CE} = -2\text{ V}; I_C = -2\text{ A}$	[1]	150	230	-	
		$V_{CE} = -2\text{ V}; I_C = -4\text{ A}$	[1]	120	170	-	
		$V_{CE} = -2\text{ V}; I_C = -6\text{ A}$	[1]	60	100	-	
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = -0.5\text{ A}; I_B = -50\text{ mA}$	[1]	-	-35	-50	mV
		$I_C = -1\text{ A}; I_B = -50\text{ mA}$	[1]	-	-65	-90	mV
		$I_C = -1\text{ A}; I_B = -10\text{ mA}$	[1]	-	-130	-190	mV
		$I_C = -2\text{ A}; I_B = -40\text{ mA}$	[1]	-	-165	-230	mV
		$I_C = -4\text{ A}; I_B = -200\text{ mA}$	[1]	-	-210	-300	mV
		$I_C = -4\text{ A}; I_B = -400\text{ mA}$	[1]	-	-160	-230	mV
		$I_C = -4.5\text{ A}; I_B = -225\text{ mA}$	[1]	-	-265	-375	mV
$R_{CEsat}$	collector-emitter saturation resistance	$I_C = -4\text{ A}; I_B = -200\text{ mA}$	[1]	-	53	75	$\text{m}\Omega$
		$I_C = -2\text{ A}; I_B = -40\text{ mA}$	[1]	-	82	115	$\text{m}\Omega$
$V_{BEsat}$	base-emitter saturation voltage	$I_C = -1\text{ A}; I_B = -100\text{ mA}$	[1]	-	-0.81	-0.9	V
		$I_C = -4\text{ A}; I_B = -400\text{ mA}$	[1]	-	-0.93	-1.05	V
$V_{BEon}$	base-emitter turn-on voltage	$V_{CE} = -2\text{ V}; I_C = -2\text{ A}$	[1]	-	-0.77	-0.85	V
$t_d$	delay time	$V_{CC} = -12.5\text{ V}; I_C = -3\text{ A}; I_{Bon} = -0.15\text{ A}; I_{Boff} = 0.15\text{ A}$	-	15	-	ns	
$t_r$	rise time		-	65	-	ns	
$t_{on}$	turn-on time		-	80	-	ns	
$t_s$	storage time		-	225	-	ns	
$t_f$	fall time		-	95	-	ns	
$t_{off}$	turn-off time		-	320	-	ns	
$f_T$	transition frequency	$V_{CE} = -10\text{ V}; I_C = -100\text{ mA}; f = 100\text{ MHz}$	-	130	-	MHz	
$C_c$	collector capacitance	$V_{CB} = -10\text{ V}; I_E = I_C = 0\text{ A}; f = 1\text{ MHz}$	-	90	120	pF	

[1] Pulse test:  $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02$ .







8. Test information

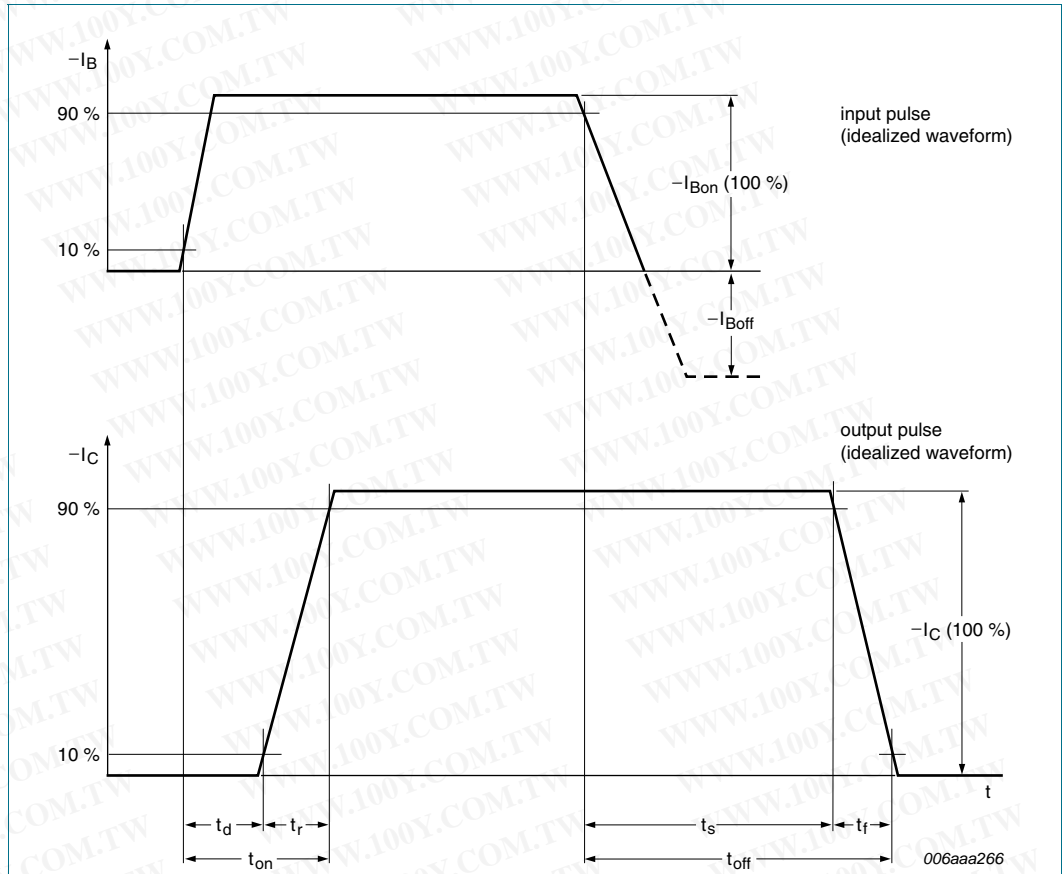


Fig 13. BISS transistor switching time definition

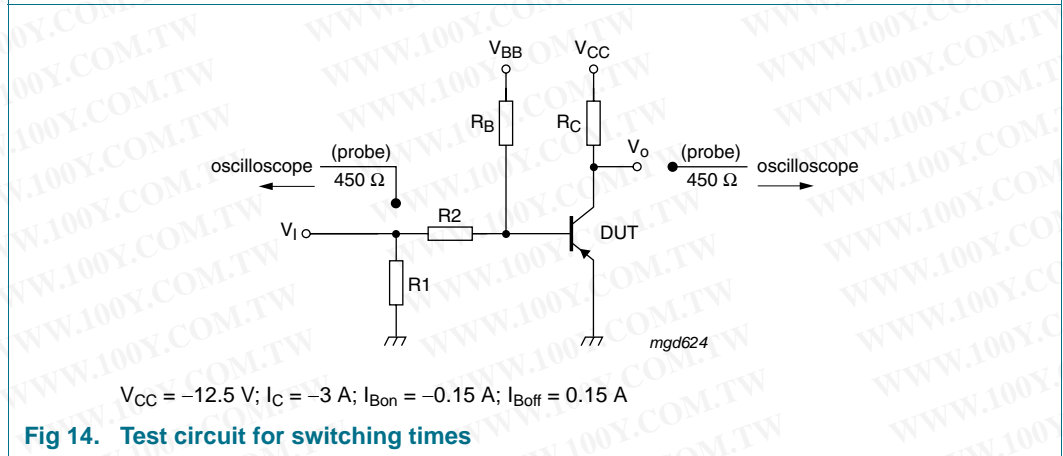
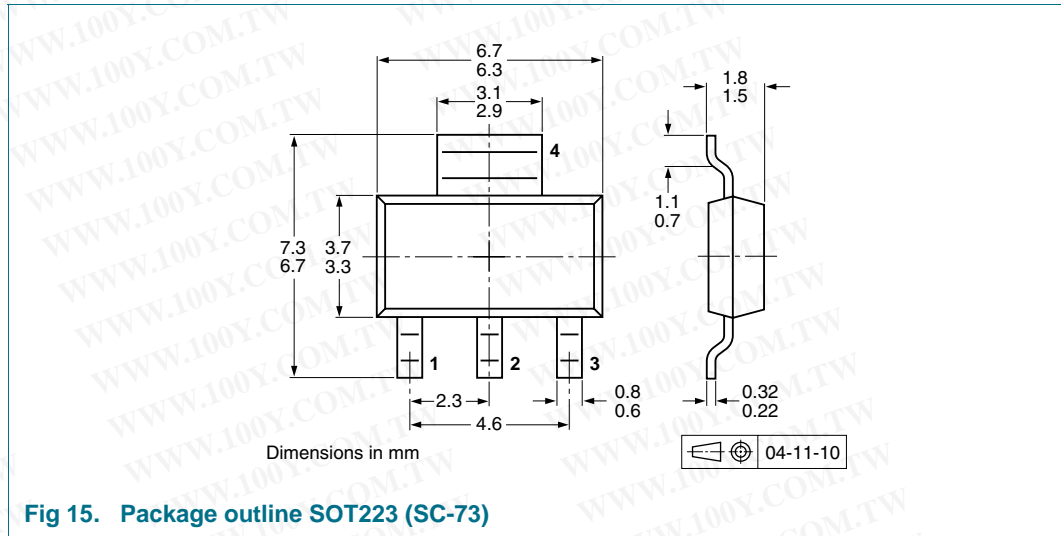


Fig 14. Test circuit for switching times

## 9. Package outline



**Fig 15. Package outline SOT223 (SC-73)**

## 10. Packing information

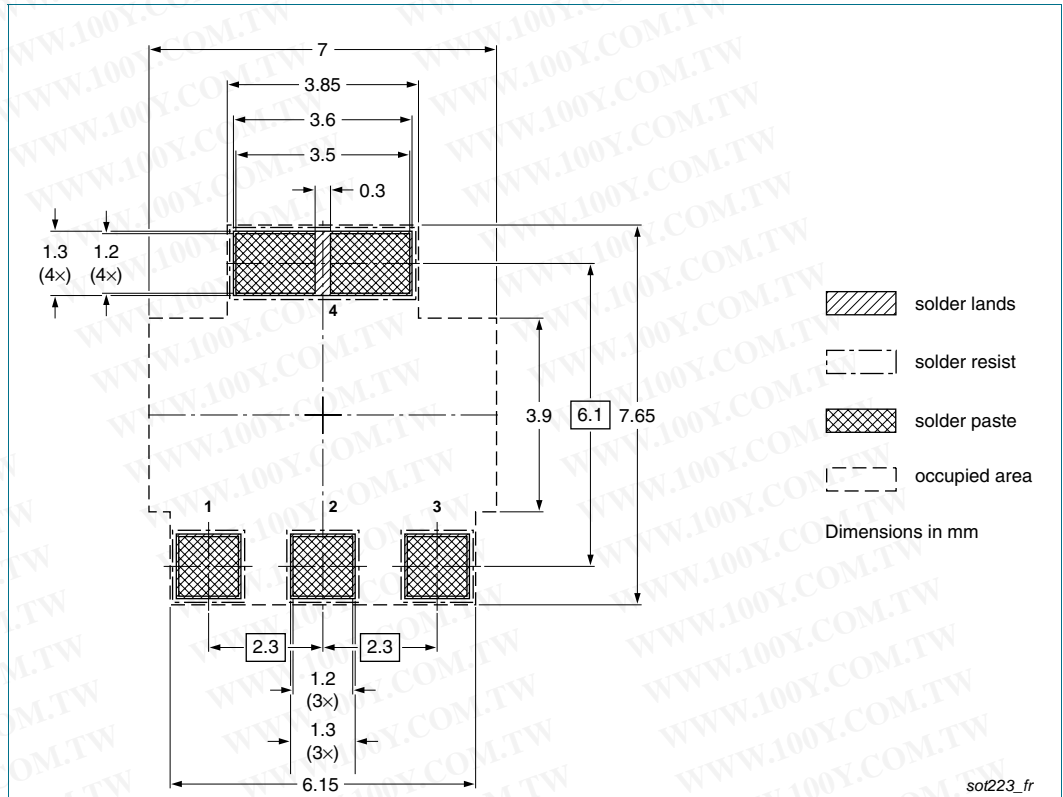
**Table 8. Packing methods**

The indicated -xxx are the last three digits of the 12NC ordering code.<sup>[1]</sup>

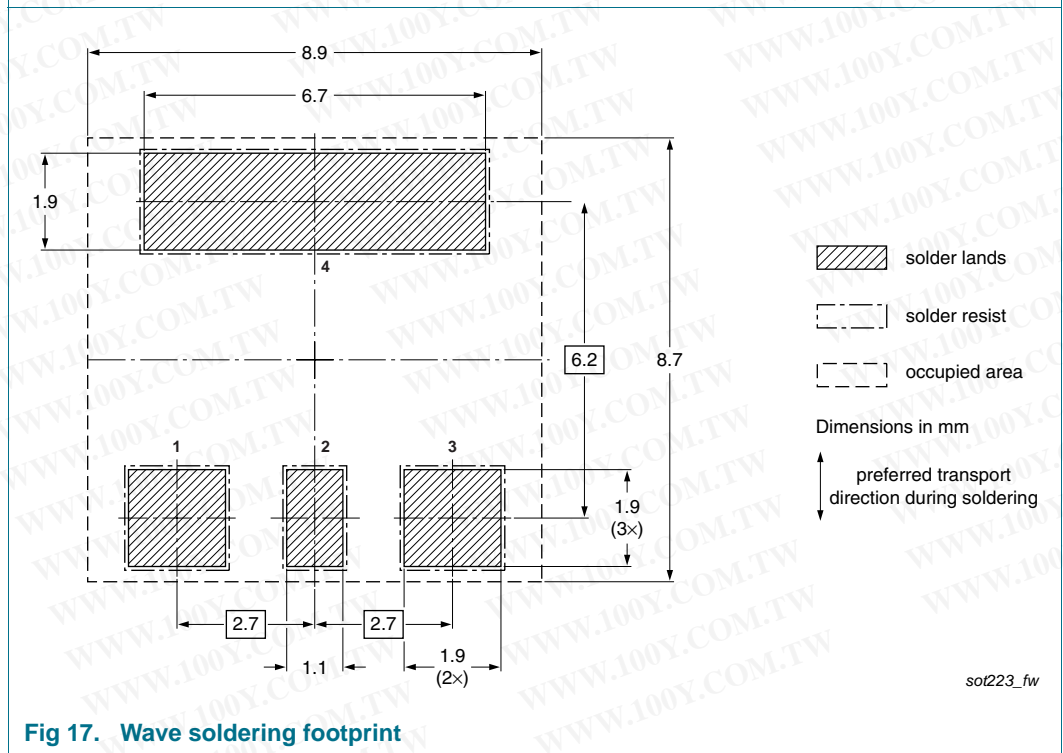
Type number	Package	Description	Packing quantity	
			1000	4000
PBSS304PZ	SOT223	8 mm pitch, 12 mm tape and reel	-115	-135

[1] For further information and the availability of packing methods, see [Section 14](#).

**11. Soldering**



**Fig 16. Reflow soldering footprint**



**Fig 17. Wave soldering footprint**

## 12. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PBSS304PZ_2	20091208	Product data sheet	-	PBSS304PZ_1
Modifications:	<ul style="list-style-type: none"> <li>This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content.</li> <li><a href="#">Figure 16 "Reflow soldering footprint"</a>: updated</li> <li><a href="#">Figure 17 "Wave soldering footprint"</a>: updated</li> </ul>			
PBSS304PZ_1	20060919	Product data sheet	-	-

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### 13.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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[2] The term 'short data sheet' is explained in section "Definitions".

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